

## KB-7150T (ANSI: CEM-3)

## 覆铜箔玻璃毡布复合基层压板

## Features 特点

- 高导热率 / High thermal conductivity
- 高 CTI 值 / High CTI value
- 优良的耐热性能/ Excellent heat resistance
- 较低的 CTE (Z-axis) /Low Z-axis expansion
- 较低的吸水率 /Low moisture absorption
- 优良的耐离子迁移性能/ ANTI-CAF
- 符合 IPC-4101D/81 的规范要求 / IPC-4101 D/81 specification is applicable

## General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Method (IPC-TM-650) 测试方法	Test Condition 处理条件	Specification (IPC-4101D) 规格值	Typical Value 典型值
Peel Strength (1 oz.) 铜箔剥离强度	N/mm	2.4.8	125°C	≥0.70	1.62
			Float 260°C / 10 Sec	≥1.05	1.60
Thermal Stress 热应力	Sec	2.4.13.1	Float 260°C/unetched	≥10	120
Bow / Twist 弯弓度/翘曲度	%	2.4.22.1	A	≤ 1.0	0.17 / 0.35
Flexural Strength 抗弯强度	N/mm <sup>2</sup>	2.4.4	Length direction	≥276	450
			Cross direction	≥186	390
Flammability 燃烧性	Rating	UL94	UL94	UL94 V-0	V-0
Glass Transition (Tg) 玻璃化转变温度	°C	2.4.25	E-2/105 DSC	≥130	136
Surface Resistivity 表面电阻	MΩ	2.5.17.1	C-96/35/90	≥1.0×10 <sup>4</sup>	1.0×10 <sup>7</sup>
Volume Resistivity 体积电阻	MΩ-cm	2.5.17.1	C-96/35/90	≥1.0×10 <sup>6</sup>	1.0×10 <sup>9</sup>
Dielectric Constant 介电常数	—	2.5.5.2	Etched/@1 MHZ	≤5.4	4.6
Loss Tangent 介质损耗	—	2.5.5.2	Etched/@1 MHZ	≤0.035	0.020
Arc Resistance 耐电弧性	Sec	2.5.1	D-48/50+D-0.5/23	≥60	125
Moisture Absorption 吸水率	%	2.6.2.1	D-24/23	≤0.50	0.20
Z-Axis Expansion Z-轴热膨胀系数	ppm/°C	2.4.24	Alpha 1	—	36
			Alpha 2	—	270
	%		50-260°C	—	3.94
Comparative Tracking Index 相比漏电起痕指数	V	IEC 60112	Etched / 0.1% NH <sub>4</sub> CL	≥600	600
Thermal Conductivity 基板导热系数	W/m·K	ASTM E-1461	LFA447	—	0.8±0.2
TD	°C	2.4.24.6	TGA	—	323

Remarks: Specimen Thickness: 1.6mm 1/1 样品厚度: 1.6mm 1/1

A = Keep the specimen originally without any process 保持原样,不作处理

C = Temperature and humidity conditioning 在恒温恒湿的空气中处理

D = Immersing in distilled water with temperature control. 浸在恒温的水中处理

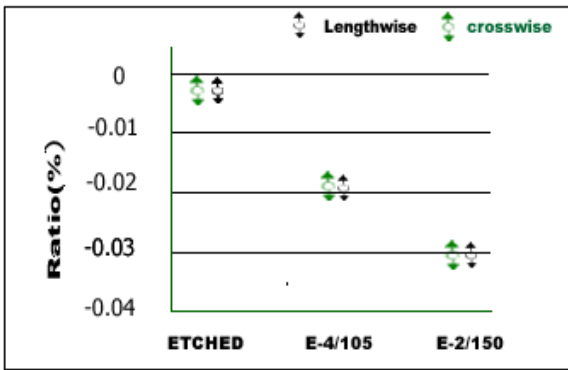
E = Temperature conditioning 在恒温的空气中处理

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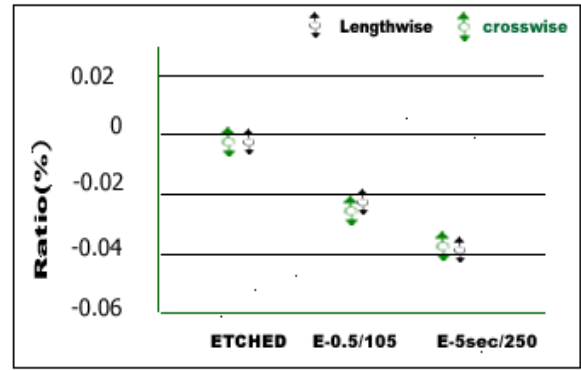
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#### Speciality Chart 板材特性图

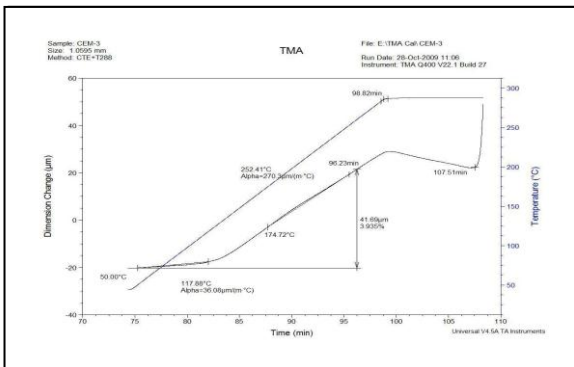
Dimensional stability 尺寸稳定性



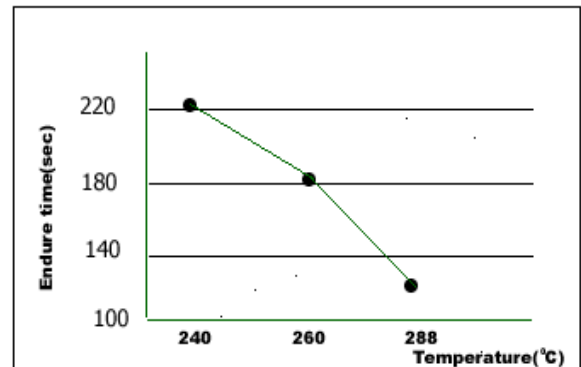
Dimensional stability-PCB process  
(size:360\*310mm)



Delamination time 分层时间



Solder Resistance 耐焊性



#### 应用领域

- 液晶 LED 背光、住宅或路灯 LED 照明、车载显示灯、仪表面板、逆变电源等

#### Applications

- LED backlight, LED light for house or street lamp, Car display lamp, Instrument panel, DC-AC

#### Purchasing Information 采购信息

Base Color 基材颜色	Thickness 厚度	Copper Cladding 铜箔厚度	Regular Size (mm) 常规尺寸
自然色 Nature	0.8mm ~1.6mm	18µm 35µm 70µm	915*1220mm (36"*48") 1020*1220mm (40"*48") 1067*1220mm (42"*48")

Note: Other sheet size and thickness could be available upon request.  
可根据客户要求提供其它尺寸和厚度